

MECHANICAL CASE OUTLINE

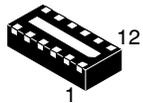
PACKAGE DIMENSIONS

ON Semiconductor®

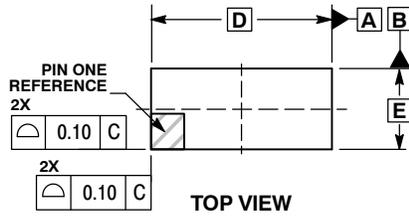


WDFN12, 3x1.35, 0.5P
CASE 511AZ-01
ISSUE O

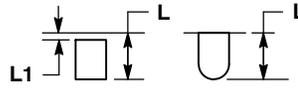
DATE 16 JUL 2010



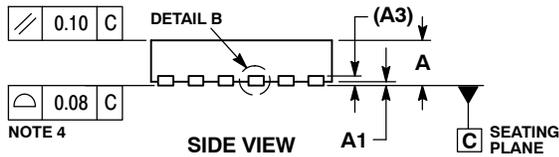
SCALE 4:1



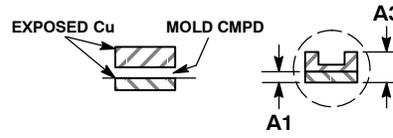
TOP VIEW



DETAIL A
ALTERNATE TERMINAL
CONSTRUCTIONS



SIDE VIEW

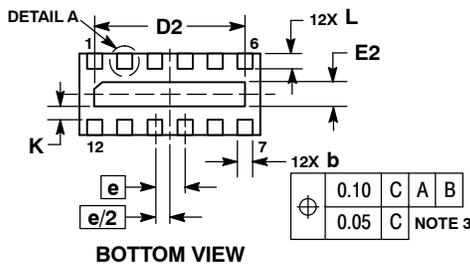


DETAIL B
ALTERNATE
CONSTRUCTIONS

NOTES:

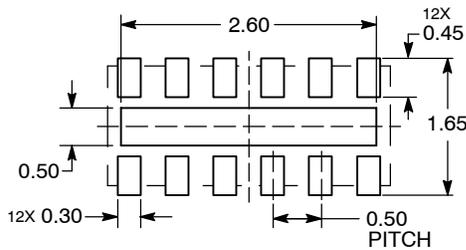
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

MILLIMETERS		
DIM	MIN	MAX
A	0.70	0.80
A1	0.00	0.05
A3	0.20	REF
b	0.20	0.30
D	3.00	BSC
D2	2.40	2.60
E	1.35	BSC
E2	0.30	0.50
e	0.50	BSC
K	0.22	REF
L	0.20	0.30
L1	---	0.15



BOTTOM VIEW

RECOMMENDED
SOLDERING FOOTPRINT*



DIMENSION: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	WDFN12, 3X1.35, 0.5P	PAGE 1 OF 2

